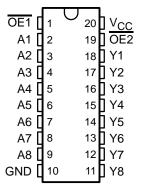
SN54HCT540, SN74HCT540 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SCLS008C - MARCH 1984 - REVISED MARCH 2003

- Operating Voltage Range of 4.5 V to 5.5 V
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 12 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible
- High-Current 3-State Outputs Interface Directly With System Bus or Can Drive Up To 15 LSTTL Loads
- Data Flow-Through Pinout (All Inputs on Opposite Side From Outputs)

SN54HCT540 . . . J PACKAGE SN74HCT540 . . . DW OR N PACKAGE (TOP VIEW)



description/ordering information

These octal buffers and line drivers are designed to have the performance of the 'HCT240 devices and a pinout with inputs and outputs on opposite sides of the package. This arrangement greatly facilitates printed circuit board layout.

The 3-state control gate is a 2-input NOR. If either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all eight outputs are in the high-impedance state. The 'HCT540 devices provide inverted data at the outputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKAC	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74HCT540N	SN74HCT540N
-40°C to 85°C	SOIC - DW	Tube	SN74HCT540DW	HCT540
	SOIC - DW	Tape and reel	SN74HCT540DWR	HC1540
–55°C to 125°C	CDIP – J	Tube	SNJ54HCT540J	SNJ54HCT540J

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each buffer/driver)

	INPUTS	OUTPUT	
OE1	OE2	Y	
L	L	L	Н
L	L	Н	L
Н	X	Χ	Z
Χ	Н	Χ	Z

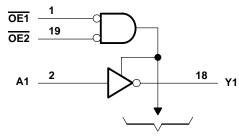


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logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 m
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 m
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 m
Continuous current through V _{CC} or GND	±70 m
Package thermal impedance, θ _{JA} (see Note 2): DW package	58°C/V
N package	69°C/V
Storage temperature range, T _{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN	54HCT5	40	SN	74HCT5	40	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	ONIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2			2			V
VIL	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V			8.0			0.8	V
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
t _t	Input transition (rise and fall) time				500			500	ns
T _A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO.	NDITIONS	Vaa	Т	A = 25°C	;	SN54H	CT540	SN74H	CT540	UNIT
PARAMETER	IESI CO	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
Va	VI = VIH or VIL	$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		V
VOH	AI = AIH OL AIL	$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		V
Voi	VI = VIH or VIL	I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	V
VOL	AI = AIH OL AIL	$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	V
lį	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0,	$V_I = V_{IH}$ or V_{IL}	5.5 V		±0.01	±0.5		±10		±5	μΑ
ICC	$V_I = V_{CC}$ or 0,	I _O = 0	5.5 V			8		160		80	μΑ
ΔI _{CC} †	One input at 0.5 V of Other inputs at 0 or		5.5 V		1.4	2.4		3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10		10	pF

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or VCC.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vaa	T _A = 25°C			SN54H	CT540	SN74H	CT540	UNIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	Α	Y	4.5 V		13	20		30		25	ns
^t pd	A	•	5.5 V		12	18		27		23	115
		Y	4.5 V		20	30		45		38	20
t _{en}	OE	'	5.5 V		18	27		41		34	ns
.	ŌĒ	V	4.5 V		19	30		45		38	20
^t dis	OE	ī	5.5 V		18	27		41		34	ns
+.		Y	4.5 V		8	12		18		15	ns
t _t		•	5.5 V		7	11		16		14	115

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

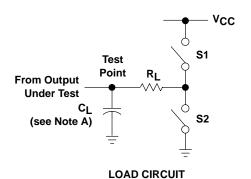
PARAMETER	FROM	TO (OUTPUT)	Vaa	T _A = 25°C			SN54H	CT540	SN74HCT540		UNIT
PARAMETER	(INPUT)		Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	Δ.	~	4.5 V		20	30		45		38	20
¹рd	^t pd A	'	5.5 V		19	27		41		34	ns
		V	4.5 V		26	40		60		50	20
^t en	ŌĒ	ī	5.5 V		25	36		54		45	ns
+.			4.5 V		17	42		63		53	ne
t _t		•	5.5 V		14	38		57		48	ns

operating characteristics, $T_A = 25^{\circ}C$

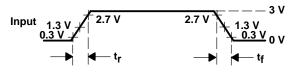
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per buffer/driver	No load	35	pF



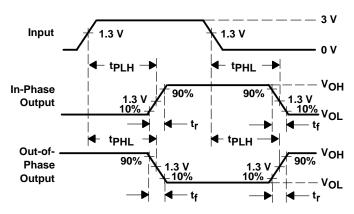
PARAMETER MEASUREMENT INFORMATION

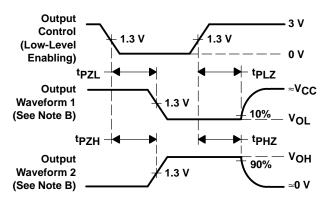


PARA	METER	RL	CL	S1	S2
tPZH		1 k Ω	50 pF or	Open	Closed
чen	t _{en} t _{PZL}		150 pF	Closed	Open
t _{PHZ}		1 k Ω	50 pF	Open	Closed
^t dis	tPLZ	1 K22	30 pi	Closed	Open
t _{pd} or	t _{pd} or t _t		50 pF or 150 pF	Open	Open



VOLTAGE WAVEFORM INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS PROPAGATION DELAY AND OUTPUT RISE AND FALL TIMES

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpz and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
JM38510/65760BRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65760BRA	Samples
M38510/65760BRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65760BRA	Samples
SN54HCT540J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HCT540J	Samples
SN74HCT540DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT540	Samples
SN74HCT540DWRG4	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT540	Samples
SN74HCT540N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HCT540N	Samples
SNJ54HCT540J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54HCT540J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HCT540, SN74HCT540:

Catalog: SN74HCT540

Military: SN54HCT540

NOTE: Qualified Version Definitions:

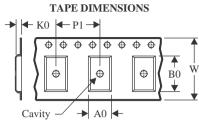
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

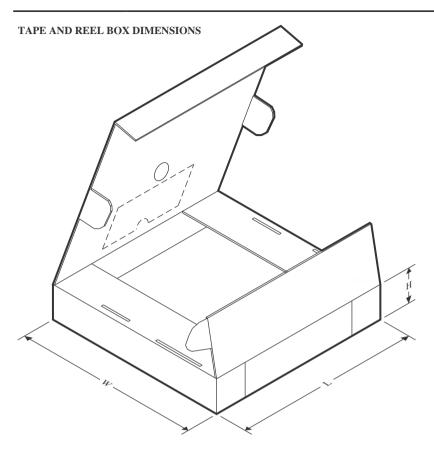


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT540DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74HCT540DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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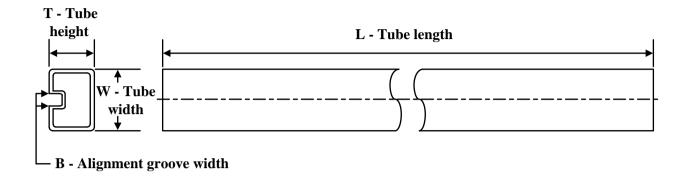
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74HCT540DWR	SOIC	DW	20	2000	367.0	367.0	45.0	
SN74HCT540DWR	SOIC	DW	20	2000	356.0	356.0	41.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74HCT540N	N	PDIP	20	20	506	13.97	11230	4.32

14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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